REMARKS

The Examiner has rejected claims 3 and 4 under 35 USC 103(a) as being unpatentable over USPN 6,432,796 to Peterson in view of JP408132258A. Applicant respectfully traverses.

Peterson discloses that lasers having wavelengths of 532 nm and 1064 nm can be used to mark the backside of a die by changing the color of the silicon exposed to the laser. In this method, the laser beam actually touches the silicon and can cause damage. Moreover, it leaves a marking that is gray and not of high contrast to the original dark color of the silicon.

JP'258 discloses a four layer marking tape comprising in order: a substrate layer, a transparent adhesive layer, a color layer that is wavelength absorptive, and a transparent cover layer. A laser is used to irradiate through the top transparent layer and form a marking in the color layer. The substrate layer is separated from the top three layers and the adhesive, color and top layers are then adhered to the object to be marked through the adhesive layer.

These references alone or in combination do not make applicant's invention obvious. Applicant's invention relates to spraying or jetting an adhesive composition containing a colored filler directly onto the inactive surface of a silicon wafer or die.

The sprayability of the instant composition is an advantage over the JP'258 method in that the wafer or die is not contacted with as much mechanical force as is used to manually or robotically apply the marking layers of the JP patent.

Further, only one layer of material is sprayed, that being the adhesive loaded with a colored filler. The filler settles by gravity to the lower side of the adhesive layer allowing the laser to etch into the adhesive and expose the color. The color can be chosen for as much contrast as desired.

Thus, the process of applying the material for marking a semiconductor die as disclosed and claimed by applicant is not obvious from the teachings of the two cited references. There is nothing in those references to suggest spraying a color filled adhesive directly onto the semiconductor; the instant invention does not rely on a substrate or a cover layer; and the adhesive and color are prepared as one composition, allowing gravity to separate them when on the object to be marked. .

In view of the above reasoning, applicant respectfully urges the Examiner to the conclusion that the claims as presented are in condition for allowance.

End of Remarks.